

IN THE CLAIMS

1. – 24. (Cancelled).

25. (Previously Added) An apparatus for use in a data processing device, comprising:
an integrated circuit (IC) package having a plurality of leads extended from the IC
package;
a first receptacle for receiving the IC package, the first receptacle including a first
opening to receive the plurality of leads when the IC package is inserted into the
first receptacle through a second opening disposed away from the first opening;
and
a second receptacle disposed on the data processing device for receiving the first
receptacle, the second receptacle having a plurality of contacts,
wherein the plurality leads of the IC package directly contact, via the first opening, with
the plurality of contacts of the second receptacle respectively when the first
receptacle is inserted into the second receptacle.

26. (Previously Added) The apparatus of claim 25, wherein the first opening is a front
opening.

27. (Previously Added) The apparatus of claim 25, wherein the second opening is a back
opening such that the IC package is inserted into the first receptacle from a back of the first
receptacle.

28. (Previously Added) The apparatus of claim 25, wherein the second opening is a bottom opening such that the IC package is inserted into the first receptacle from a bottom of the first receptacle using a rotating movement.

29. (Previously Added) The apparatus of claim 25, wherein the first receptacle provides a physical and electrostatic discharge protection for the IC package.

30. (Previously Added) The apparatus of claim 25, wherein the first receptacle further comprises at least one stop disposed at the second opening to securely hold the IC package within the first receptacle.

31. (Previously Added) A method for use in a data processing device, comprising:
providing an integrated circuit (IC) package having a plurality of leads extended from the IC package;
providing a first receptacle for receiving the IC package, the first receptacle including a first opening and a second opening disposed away from the first opening;
inserting the IC package into the first receptacle through the second opening, such that the first opening receives the plurality of leads of the IC package; and
inserting the first receptacle with the inserted IC package into a second receptacle disposed on the data processing device, the second receptacle having a plurality of contacts,
wherein the plurality of leads of the IC package directly contact, via the first opening, with the plurality of contacts of the second receptacle respectively when the first receptacle is inserted into the second receptacle.

32. (Previously Added) The method of claim 31, wherein the first opening is a front opening.

33. (Previously Added) The method of claim 31, wherein the second opening is a back opening such that the IC package is inserted into the first receptacle from a back of the first receptacle.

34. (Previously Added) The method of claim 31, wherein the second opening is a bottom opening such that the IC package is inserted into the first receptacle from a bottom of the first receptacle using a rotating movement.

35. (Previously Added) The method of claim 31, wherein the first receptacle provides a physical and electrostatic discharge protection for the IC package.

36. (Previously Added) The method of claim 31, wherein the first receptacle further comprises at least one stop disposed at the second opening to securely hold the IC package within the first receptacle.

37. (New) The apparatus of claim 25, wherein the first receptacle having the inserted IC package is removable from the second receptacle without soldering.

38. (New) The apparatus of claim 25, wherein the second receptacle encapsulates at least a portion of the first receptacle when the first receptacle is inserted into the second receptacle.

39. (New) The apparatus of claim 25, wherein the second receptacle is capable of being disposed on the data processing device via soldering and wherein the first receptacle does not directly contact with the data processing device when the first receptacle is inserted into the second receptacle.

40. (New) The method of claim 31, wherein the first receptacle having the inserted IC package is removable from the second receptacle without soldering.

41. (New) The method of claim 31, wherein the second receptacle encapsulates at least a portion of the first receptacle when the first receptacle is inserted into the second receptacle.

42. (New) The method of claim 31, wherein the second receptacle is capable of being disposed on the data processing device via soldering and wherein the first receptacle does not directly contact with the data processing device when the first receptacle is inserted into the second receptacle.